

3. (New) The electronics system of claim 2, wherein said electromagnetic coupler is loosely coupled to said transmission line such that a signal in said electromagnetic coupler induces a corresponding signal in said transmission line that is attenuated by at least about 20 decibels.
4. (New) The electronics system of claim 2, wherein said electromagnetic coupler is loosely coupled to said transmission line such that a signal in said electromagnetic coupler induces a corresponding signal in said transmission line that is attenuated by between about 10 decibels and about 40 decibels.
5. (New) The electronics system of claim 2, wherein at least one of said plurality of electronic components is an integrated circuit.
6. (New) The electronics system of claim 5, wherein the electromagnetic coupler of said integrated circuit is smaller than said integrated circuit.
7. (New) The electronics system of claim 5, wherein the electromagnetic coupler of said integrated circuit is integrated with a packaging of said integrated circuit.
8. (New) The electronics system of claim 5 further comprising shielding material disposed between circuitry on said integrated circuit and the electromagnetic coupler of said integrated circuit.
9. (New) The electronics system of claim 8, wherein said shielding includes a gap disposed adjacent the electromagnetic coupler of said integrated circuit.
10. (New) The electronics system of claim 2 wherein at least one of said electromagnetic couplers is grounded at one end.
11. (New) The electronics system of claim 10, wherein each of said electromagnetic couplers is grounded at one end.

12. (New) The electronics system of claim 2, wherein at least two of said plurality of electronic components are integrated circuits.
13. (New) The electronics system of claim 12 further comprising a substrate, wherein said transmission line comprises a conductive material disposed on said substrate and each of said integrated circuits is attached to said substrate.
14. (New) The electronics system of claim 2, wherein at least one of said plurality of electronic components is a first circuit board.
15. (New) The electronics system of claim 14, wherein said transmission line is disposed on a second circuit board.
16. (New) The electronics system of claim 2 further including shielding material disposed to at least partially shield said transmission line.
17. (New) The electronics system of claim 16, wherein said shielding material includes gaps through which said electromagnetic couplers of said plurality of electronic components electromagnetically couple to said transmission line.
18. (New) The electronics system of claim 2 further including a plurality of transmission lines.
19. (New) The electronics system of claim 18, wherein at least one of said plurality of electronic components includes a plurality of electromagnetic couplers.
20. (New) The electronics system of claim 19, wherein each said electromagnetic coupler of said at least one electronic component is electromagnetically coupled to a corresponding one of said plurality of transmission lines.

21. (New) The electronics system of claim 18 further including shielding material disposed between each of said plurality of transmission lines.
22. (New) The electronics system of claim 2, wherein said plurality of electronic components are disposed along said transmission line such that the electromagnetic couplers of each of said electronic components are spaced no more than about ten millimeters from said transmission line.
23. (New) The electronics system of claim 2, wherein said transmission line is passive.
- 24 (New) The electronics system of claim 2, wherein said transmission line does not physically contact an active electronic device.
25. (New) The electronics system of claim 2, wherein said transmission line is driven only by electronic devices that are electromagnetically coupled to said transmission line.
26. (New) An electronics system comprising:
 - a first integrated circuit comprising a first electromagnetic coupler; and
 - a second integrated circuit comprising a second electromagnetic coupler,said first integrated circuit and said second integrated circuit disposed such that said first electromagnetic coupler and said second electromagnetic coupler are spaced from each other but within sufficient proximity to be electromagnetically coupled,
whereby data provided to said first electromagnetic coupler is contactlessly communicated to said second electromagnetic coupler.
27. (New) The electronics system of claim 26, wherein said first electromagnetic coupler is spaced no more than approximately ten millimeters from said second electromagnetic coupler.
28. (New) The electronics system of claim 26 further including a substrate, wherein said first integrated circuit and said second integrated circuit are mounted to said substrate.

29. (New) The electronics system of claim 26 further including a substrate, wherein said first integrated circuit is mounted to said substrate and said second integrated circuit is mounted to said first integrated circuit.
30. (New) The electronics system of claim 26, wherein said first electromagnetic coupler is smaller than said first integrated circuit.
31. (New) The electronics system of claim 30, wherein said second electromagnetic coupler is smaller than said second integrated circuit.
32. (New) The electronics system of claim 26 further including shielding material disposed between circuitry on said first integrated circuit and said first electromagnetic coupler.
33. (New) The electronics system of claim 32 further including shielding material disposed between circuitry on said second integrated circuit and said second electromagnetic coupler.
34. (New) The electronics system of claim 26 further including shielding material disposed to at least partially shield a contactless communication channel between said first electromagnetic coupler and said second electromagnetic coupler.
35. (New) The electronics system of claim 26 further comprising a third integrated circuit comprising a third electromagnetic coupler disposed to be electromagnetically coupled with at least one of said first electromagnetic coupler and said second electromagnetic coupler.
36. (New) An electronics system comprising:
 - a transmission line;
 - a plurality of electronic components; and
 - a plurality of coupling means each for loosely electromagnetically coupling with at least a 10 decibel attenuation one of said electronic components with said transmission line

37. (New) The electronics system of claim 36 further comprising shielding means for shielding said transmission line.

38. (New) The electronics system of claim 36 further comprising shielding means associated with each of said electronics components for shielding each said electronic component.

39. (New) The electronics system of claim 36, wherein said transmission line is disposed on a substrate, and said electronic components comprise integrated circuits disposed on said substrate.

40. (New) An electronics system comprising:

a first integrated circuit;
style="padding-left: 40px;"/>a second integrated circuit; and
electromagnetic coupling means for providing a contactless direct electromagnetic coupling between said first integrated circuit with said second integrated circuit.

41. (New) The electronics system of claim 40 further comprising first shielding means for shielding said first integrated circuit.

42. (New) The electronics system of claim 41 further comprising second shielding means for shielding said second integrated circuit.